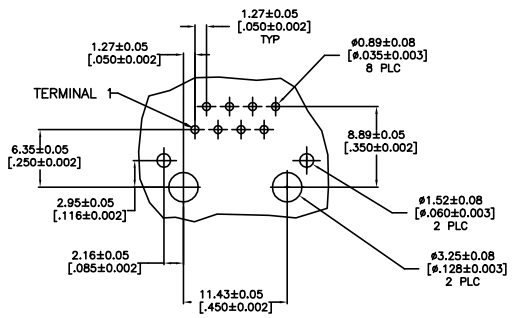
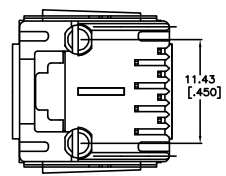
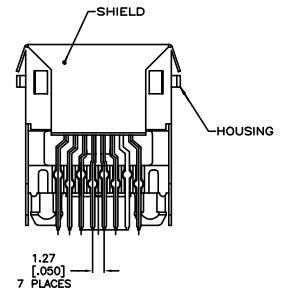
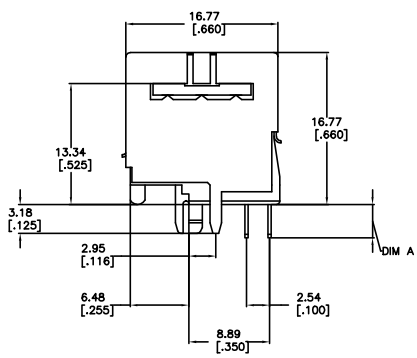
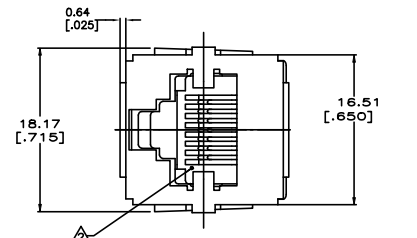
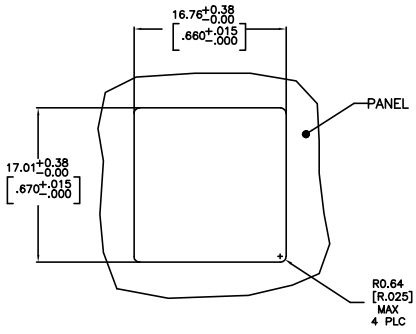


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REVISIONS			
REV	DATE	BY	APPV
E1	ECO-19-013839		05SEP2019 IT SH



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT COMPONENT SIDE SHOWN



RECOMMENDED PANEL CUTOUT

- 1 MATERIAL:
HOUSING - POLYESTER MOLDING COMPOUND, COLOR: BLACK
TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.
- 2 CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.
- 3 MATERIAL:
HOUSING - HIGH TEMP THERMOPLASTIC-LCP, COLOR: BLACK
TERMINALS - 0.35[.0138] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MIN THICK NICKEL UNDERPLATE
SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0µm [.000120] MIN THICK REFLOWED TIN.
- 4 RECOMMENDED DIAMETER OF POSITION HOLE ON PCB FOR 5557969-3, 5557969-4 IS 3.175±0.08MM
- 5 SAME AS 5557969-3 BUT RESTRICTED TO CUSTOMNER

MATERIAL	DIM A	PART NUMBER
1	2.79-3.56 [1.25±.015]	5557969-4
4	2.79-3.56 [1.25±.015]	5557969-3
1	2.79-3.30 [1.20±.010]	5557969-2
1	2.79-3.56 [1.25±.015]	5557969-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DESIGNED BY: A. FERNANDEZ-RODRIGUEZ CHECKED BY: J. WESTMAN DRAWN BY: S. ELKINGER DATE: 108-1163 PRODUCT SPEC: 114-2048		TE TE Connectivity MODULAR JACK ASSEMBLY, TOP ENTRY, 8 POSITION, FLANGELESS, SHIELDED, WITH PANEL	
DIMENSIONS (mm) (INCHES)	0 PLC * - 1 PLC * - 2 PLC * 0.15(0.005) 3 PLC * - 4 PLC * - 5 PLC * -	SIZE: A1 DATE CODE: 0000000 CUSTOMER DRAWING	SCALE: 4:1	SHEET: 1 OF 1 REV: E1	RESTRICTED TO: -

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)